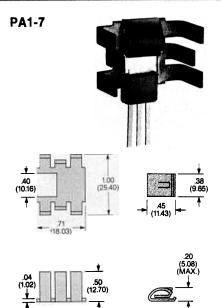
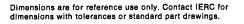
Free-standing heat dissipator and clip assembly

- Beryllium copper clip is designed to provide high clamping pressure, which assures low thermal resistance between dissipator and semiconductor, allowing a 150% power increase in natural convection to more than 400% in forced air.
- Clip may be used alone to attach semiconductor to a customer designed heat conduction plane.
- Free-standing assembly can be mounted either vertically or horizontally on board

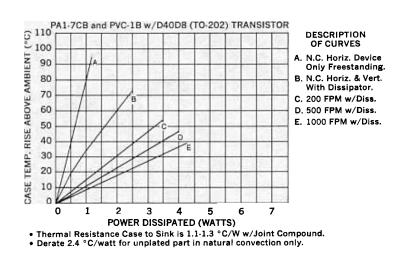
--- requires no special tools or mounting hardware.

Clip's spring design firmly attaches to device and dissipator, stays attached even in severe shock and vibration environments.



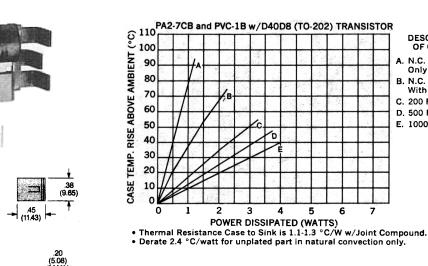


PA2-7



Ordering Information

ITEM		IER	Semiconductor	Max.		
	Unplated	Black Cadmium	Comm'l. Black Anodize	Mil. Black Anodize	Accommodated	Weight (Grams)
Dissipator Clip	PA1-7U PVC-1U	N/A PVC-1B	PA1-7CB N/A	PA1-7B N/A	T0-202 T0-202	2.0 0.7



OF CURVES N.C. Horiz. Device Only Freestanding. A. B. N.C. Horiz. & Vert. With Dissipator. C. 200 FPM w/Diss.

DESCRIPTION



1.00 (25.40) 18.03)



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

Ordering Information

ITEM		IERO	Semiconductor	Max.		
	Unplated	Black Cadmium	Comm'l. Black Anodize	Mil. Black Anodize	Accommodated	Weight (Grams)
Dissipator Clip	PA2-7U PVC-1U	N/A PVC-1B	PA2-7CB N/A	PA2-7B N/A	T0-202 T0-202	1.5 0.7

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